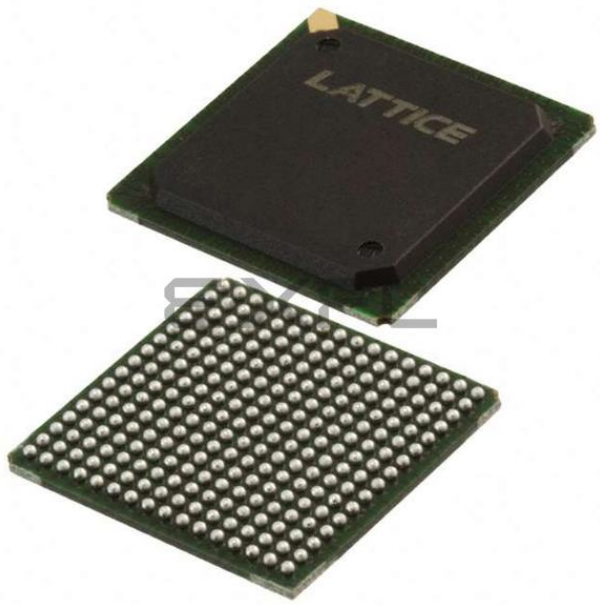
Lattice Semiconductor Corporation - M4A3-256/192-7FAC Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	192
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-256-192-7fac

Table 1. ispMACH 4A Device Features

3.3 V Devices								
Feature	**M4A3-32**	**M4A3-64**	**M4A3-96**	**M4A3-128**	**M4A3-192**	**M4A3-256**	**M4A3-384**	**M4A3-512**
Macrocells	32	64	96	128	192	256	384	512
User I/O options	32	32/64	48	64	96	128/160/192	160/192	160/192/256
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	5.5	6.5	7.5
f_{CNT} (MHz)	182	167	167	167	160	167	154	125
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	4.0	4.5	5.5
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5	3.5	5.0
Static Power (mA)	20	25/52	40	55	85	110/150	149/155	179
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

5 V Devices						
Feature	**M4A5-32**	**M4A5-64**	**M4A5-96**	**M4A5-128**	**M4A5-192**	**M4A5-256**
Macrocells	32	64	96	128	192	256
User I/O options	32	32	48	64	96	128
t_{PD} (ns)	5.0	5.5	5.5	5.5	6.0	6.5
f_{CNT} (MHz)	182	167	167	167	160	154
t_{COS} (ns)	4.0	4.0	4.0	4.0	4.5	5.0
t_{SS} (ns)	3.0	3.5	3.5	3.5	3.5	3.5
Static Power (mA)	20	25	40	55	74	110
JTAG Compliant	Yes	Yes	Yes	Yes	Yes	Yes
PCI Compliant	Yes	Yes	Yes	Yes	Yes	Yes

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32 M4A5-32	C				C, I	C, I	I	
M4A3-64/32 M4A5-64/32		C			C, I	C, I	I	
M4A3-64/64		C			C, I	C, I	I	
M4A3-96 M4A5-96		C			C, I	C, I	I	
M4A3-128 M4A5-128		C			C, I	C, I	I	
M4A3-192 M4A5-192			C		C, I	C, I	I	
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192 M4A3-256/160					C	C, I	I	
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. C = Commercial, I = Industrial

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in "product term clusters." The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.

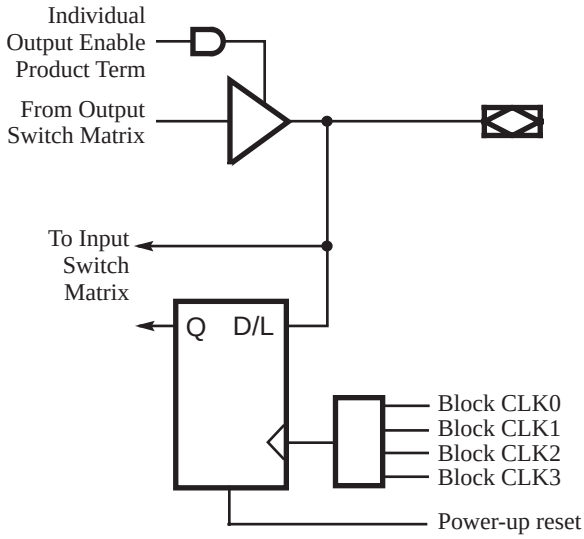


Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

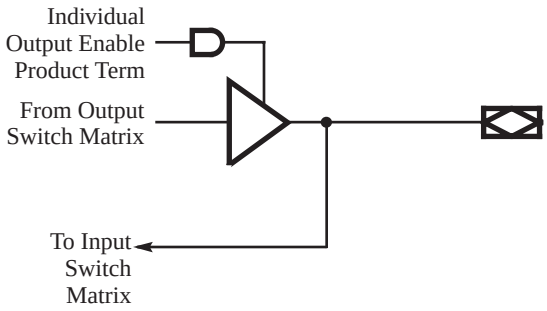


Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as "time-domain-multiplexed" data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

Input Switch Matrix

The input switch matrix (Figures 12 and 13) optimizes routing of inputs to the central switch matrix. Without the input switch matrix, each input and feedback signal has only one way to enter the central switch matrix. The input switch matrix provides additional ways for these signals to enter the central switch matrix.

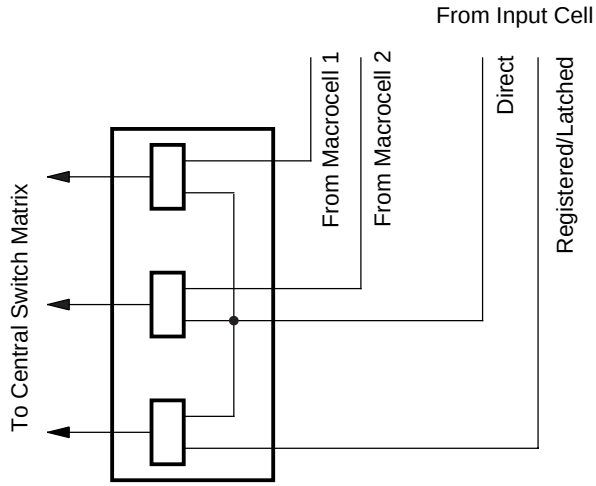


Figure 12. ispMACH 4A with 2:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

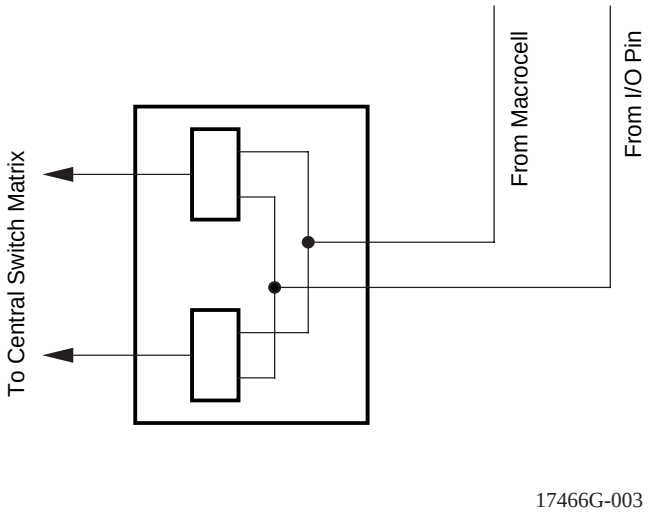


Figure 13. ispMACH 4A with 1:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

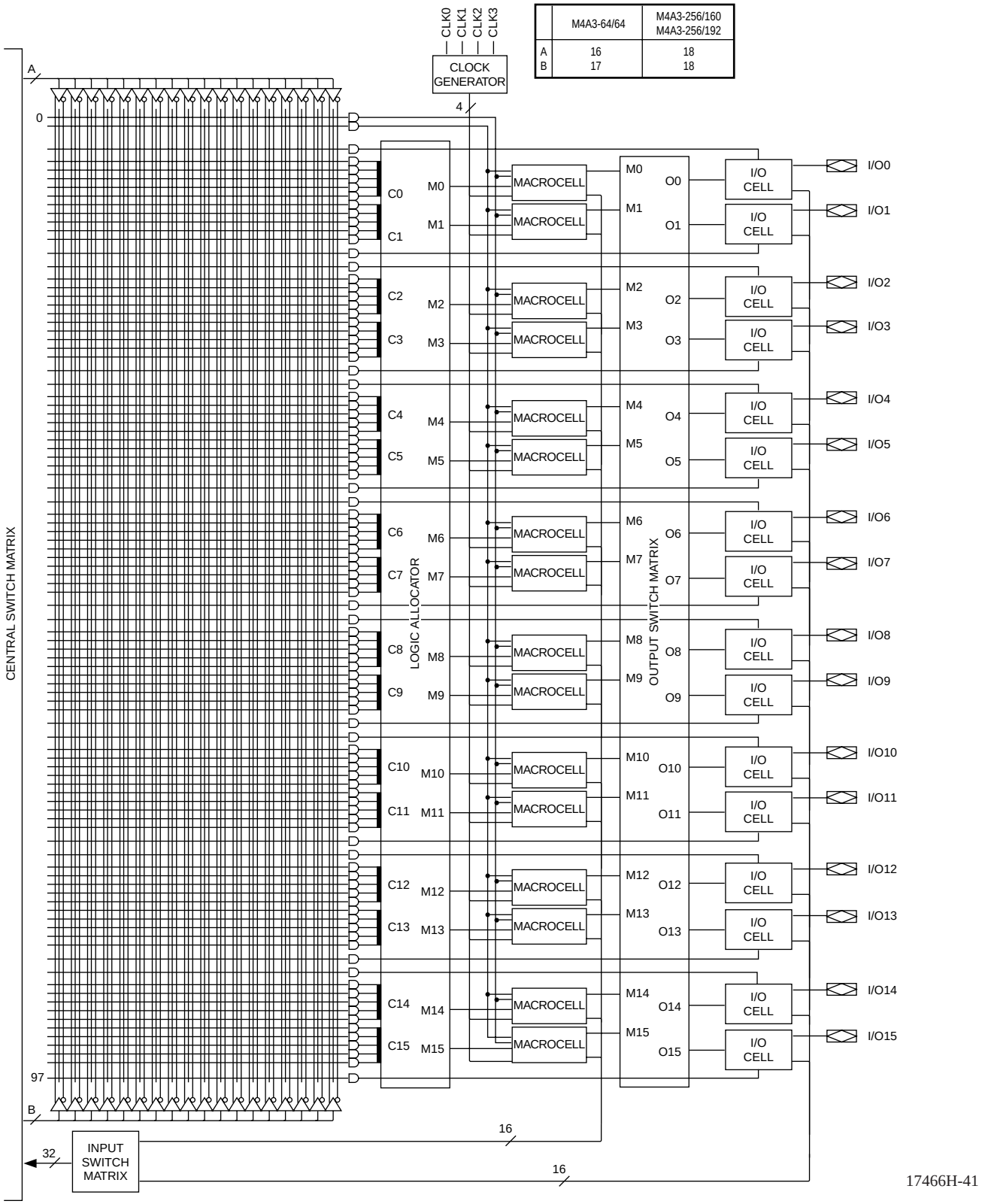


Figure 17. PAL Block for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio (except M4A (3,5)-32/32)

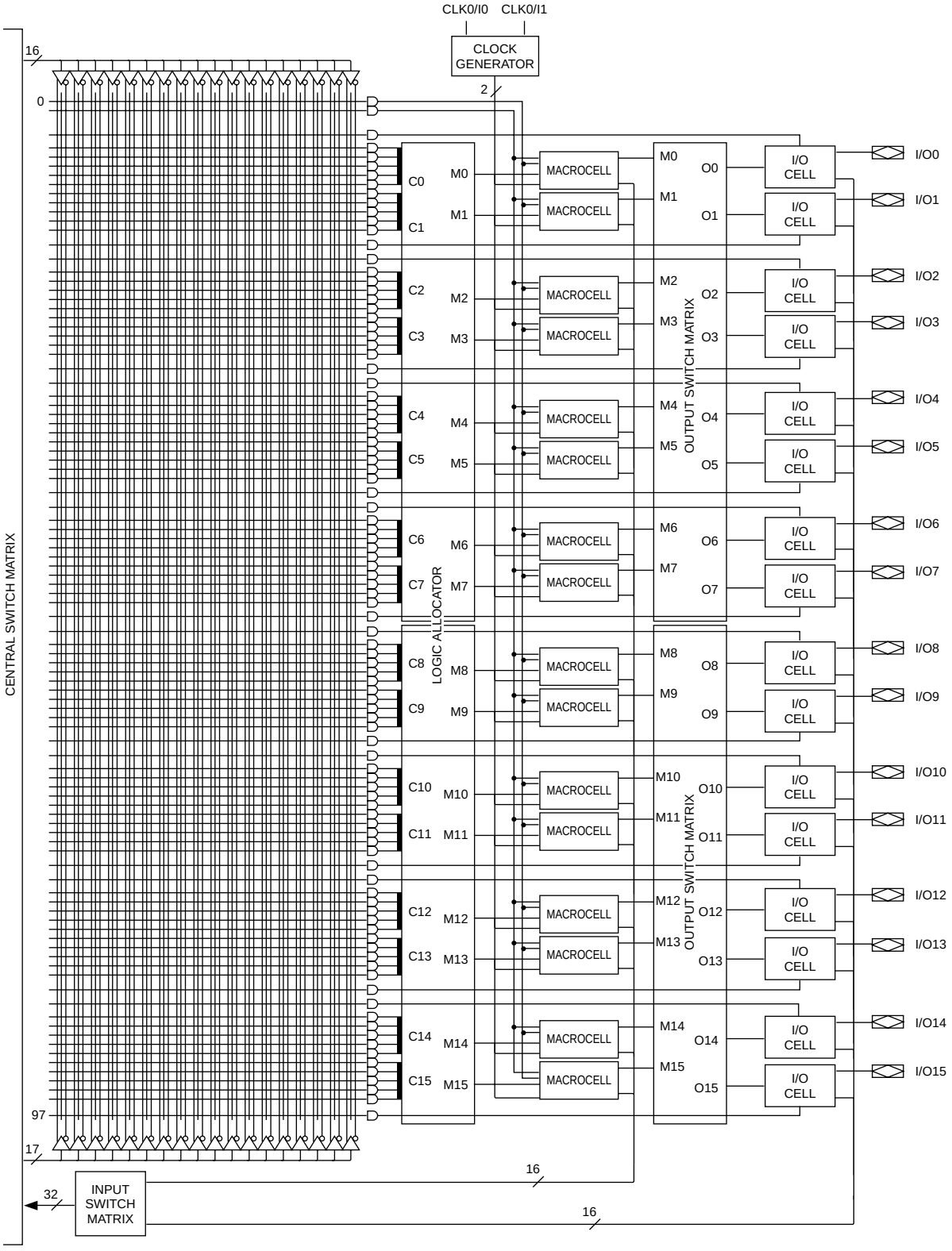
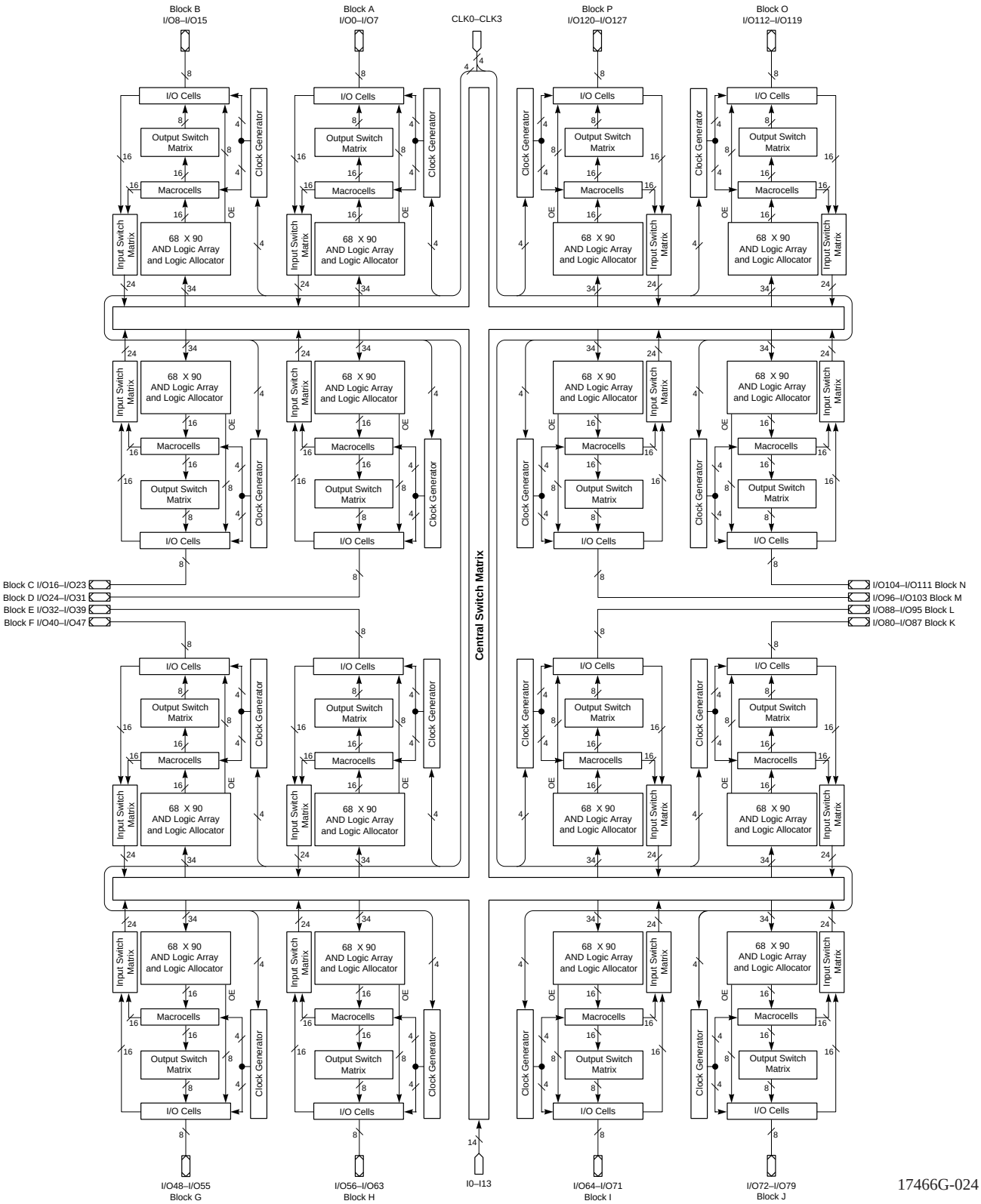


Figure 18. PAL Block for M4A (3,5)-32/32

17466H-042

BLOCK DIAGRAM – M4A(3,5)-256/128



17466G-024

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature . . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . . -55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . . . -0.5 V to +7.0 V

DC Input Voltage . . . . . -0.5 V to V_{CC} + 0.5 V

Static Discharge Voltage . . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . . 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . -40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.50 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = –3.2 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	2.4			V
		I_{OH} = -100 µA, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 5.25 V, V_{CC} = Max (Note 3)			10	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 3)			–10	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 3)			10	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max , V_{IN} = V_{IH} or V_{IL} (Note 3)			–10	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 4)	–30		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.*
3. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
4. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. V_{OUT} = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.*

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature . . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . . -55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . . . -0.5 V to +4.5 V

DC Input Voltage . . . . . -0.5 V to 6.0 V

Static Discharge Voltage . . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . . 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . -40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	I_{OH} = –100 µA	V_{CC} – 0.2			V
			I_{OH} = –3.2 mA	2.4			V
V_{OL}	Output LOW Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)	I_{OL} = 100 µA			0.2	V
			I_{OL} = 24 mA			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		–0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 3.6 V, V_{CC} = Max (Note 2)				5	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 2)				–5	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 3.6 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				5	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				–5	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 3)		–15		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
3. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.*

Notes:

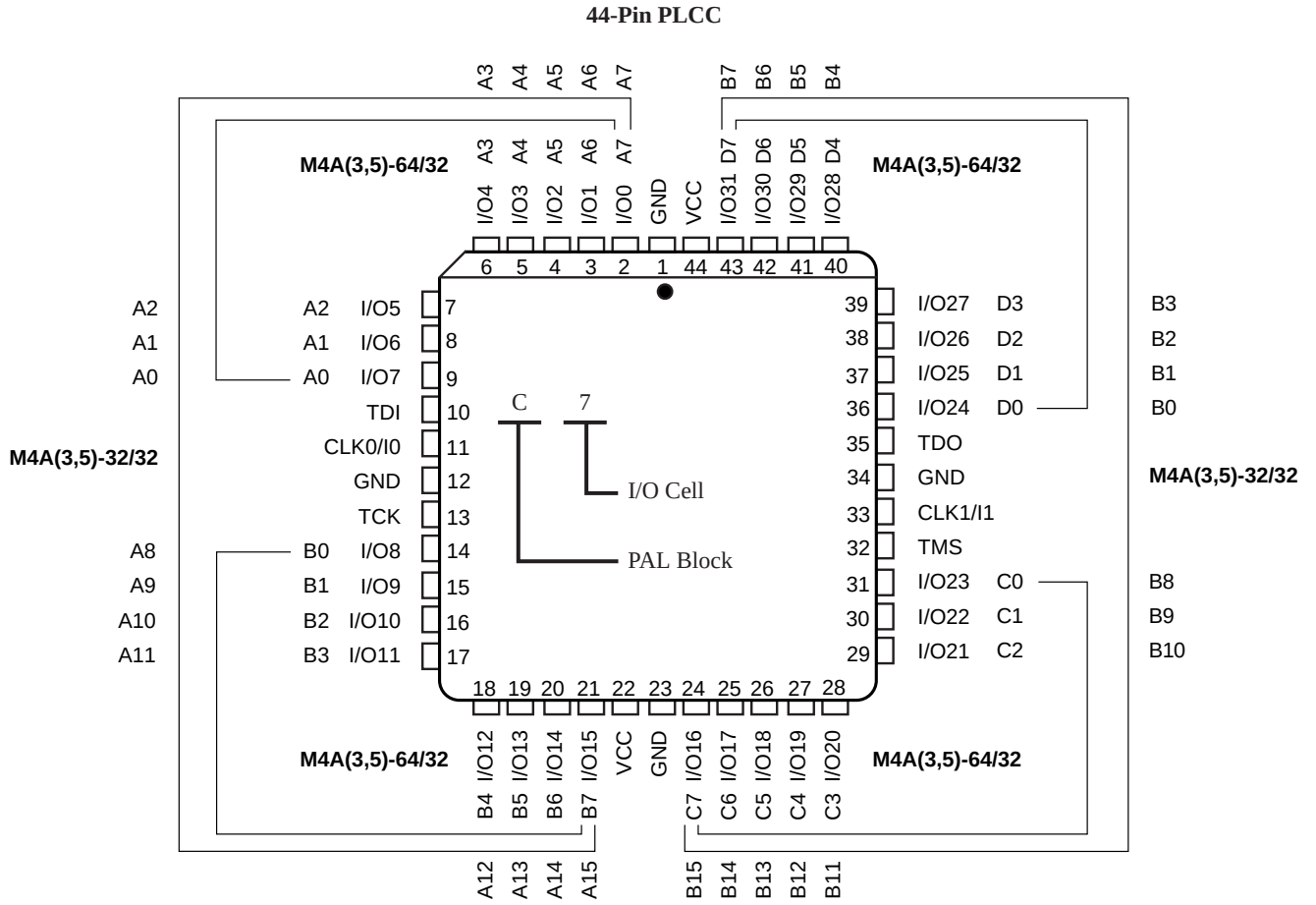
1. *See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.*
2. *This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.*

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES[1]

		-5		-55		-6		-65		-7		-10		-12		-14		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
Combinatorial Delay:																		
t_{PDi}	Internal combinatorial propagation delay		3.5		4.0		4.3		4.5		5.0		7.0		9.0		11.0	ns
t_{PD}	Combinatorial propagation delay		5.0		5.5		6.0		6.5		7.5		10.0		12.0		14.0	ns
Registered Delays:																		
t_{SS}	Synchronous clock setup time, D-type register	3.0		3.5		3.5		3.5		5.0		5.5		7.0		10.0		ns
t_{SST}	Synchronous clock setup time, T-type register	4.0		4.0		4.0		4.0		6.0		6.5		8.0		11.0		ns
t_{SA}	Asynchronous clock setup time, D-type register	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t_{SAT}	Asynchronous clock setup time, T-type register	3.0		3.0		3.0		3.5		4.5		5.0		6.0		9.0		ns
t_{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t_{HA}	Asynchronous clock hold time	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t_{COSi}	Synchronous clock to internal output		2.5		2.5		2.8		3.0		3.0		3.0		3.5		3.5	ns
t_{COS}	Synchronous clock to output		4.0		4.0		4.5		5.0		5.5		6.0		6.5		6.5	ns
t_{COAi}	Asynchronous clock to internal output		5.0		5.0		5.0		5.0		6.0		8.0		10.0		12.0	ns
t_{COA}	Asynchronous clock to output		6.5		6.5		6.8		7.0		8.5		11.0		13.0		15.0	ns
Latched Delays:																		
t_{SSL}	Synchronous latch setup time	4.0		4.0		4.0		4.5		6.0		7.0		8.0		10.0		ns
t_{SAL}	Asynchronous latch setup time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t_{HSL}	Synchronous latch hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t_{HAL}	Asynchronous latch hold time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t_{PDLi}	Transparent latch to internal output		5.5		5.5		5.8		6.0		7.5		9.0		11.0		12.0	ns
t_{PDL}	Propagation delay through transparent latch to output		7.0		7.0		7.5		8.0		10.0		12.0		14.0		15.0	ns
t_{GOSi}	Synchronous gate to internal output		3.0		3.0		3.0		3.0		3.5		4.5		7.0		8.0	ns
t_{GOS}	Synchronous gate to output		4.5		4.5		4.8		5.0		6.0		7.5		10.0		11.0	ns
t_{GOAi}	Asynchronous gate to internal output		6.0		6.0		6.0		6.0		8.5		10.0		13.0		15.0	ns
t_{GOA}	Asynchronous gate to output		7.5		7.5		7.8		8.0		11.0		13.0		16.0		18.0	ns
Input Register Delays:																		
t_{SIRS}	Input register setup time	1.5		1.5		2.0		2.0		2.0		2.0		2.0		2.0		ns
t_{HIRS}	Input register hold time	2.5		2.5		3.0		3.0		3.0		3.0		3.0		4.0		ns
t_{ICOSi}	Input register clock to internal feedback		3.0		3.0		3.0		3.0		3.5		4.5		6.0		6.0	ns
Input Latch Delays:																		
t_{SIL}	Input latch setup time	1.5		1.5		1.5		2.0		2.0		2.0		2.0		2.0		ns
t_{HIL}	Input latch hold time	2.5		2.5		2.5		3.0		3.0		3.0		3.0		4.0		ns
t_{IGOSi}	Input latch gate to internal feedback		3.5		3.5		3.8		4.0		4.0		4.0		4.0		5.0	ns
t_{PDILi}	Transparent input latch to internal feedback		1.5		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

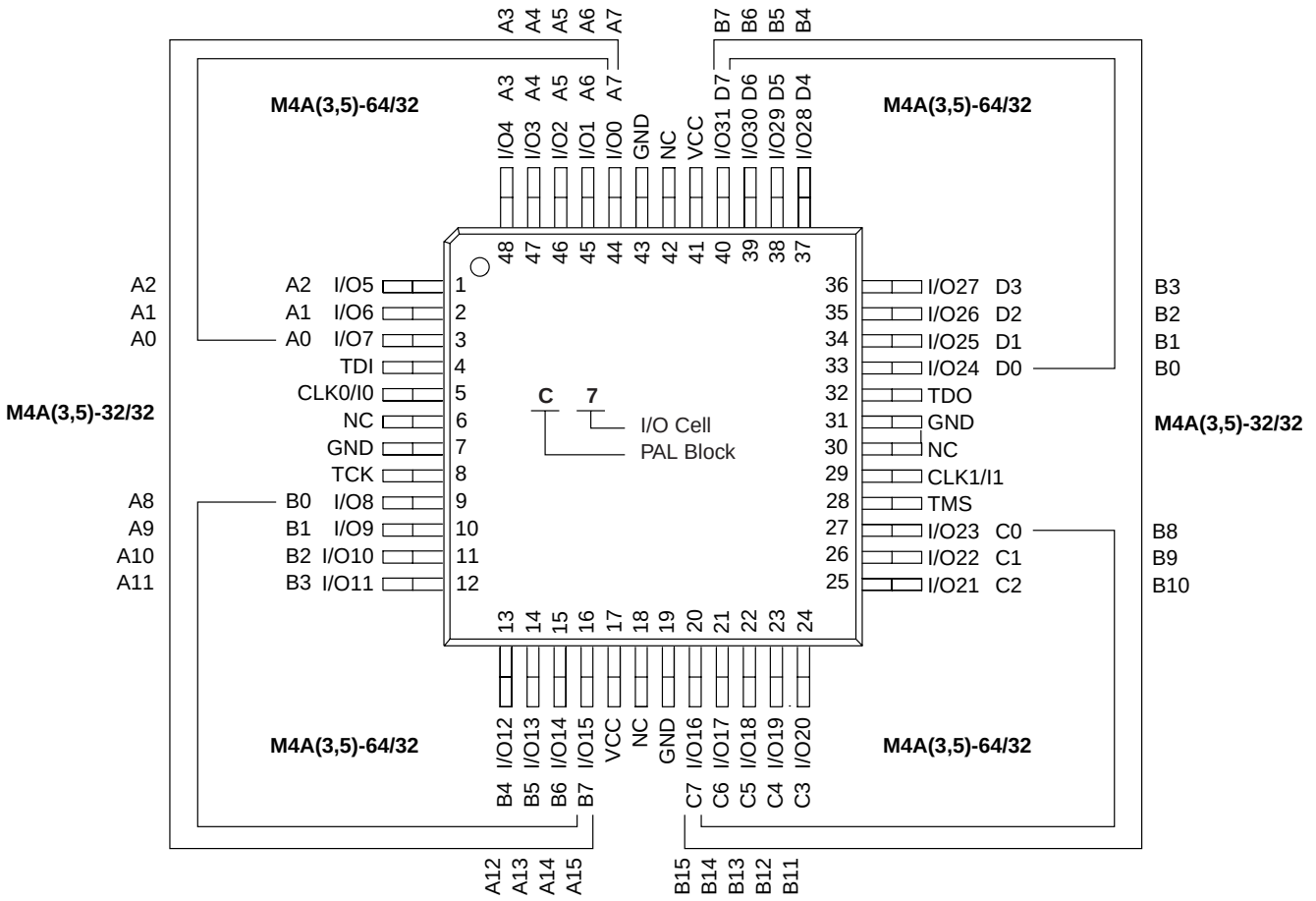
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

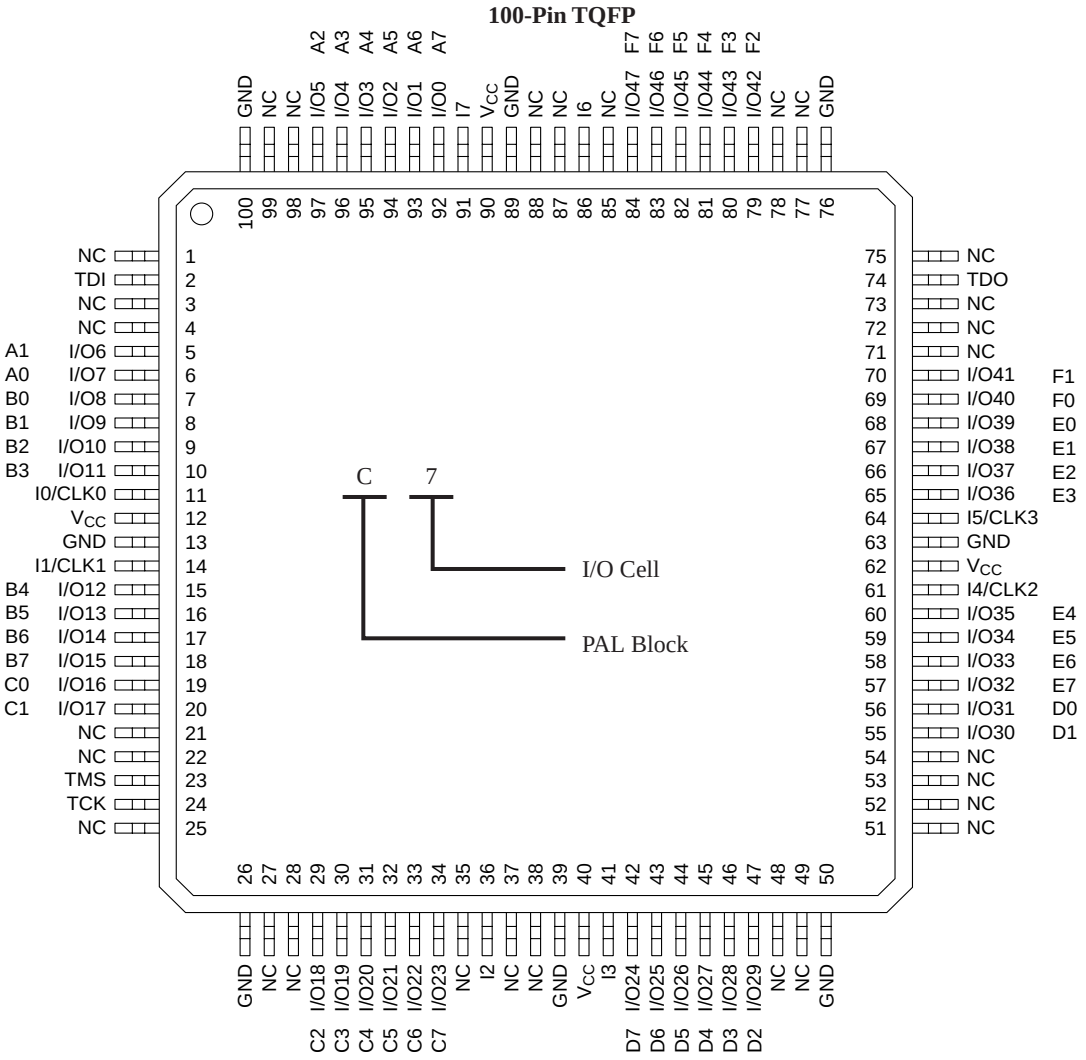
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-96/48)

Top View



17466G-029

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

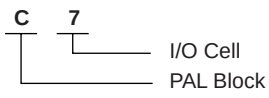
Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	**A**
B	$\overline{\text{TRST}}$	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	**B**
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	**C**
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	**D**
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	**E**
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	**F**
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	**G**
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	**H**
J	I/O47 F7	$\overline{\text{ENABLE}}$	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	**J**
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	**K**
	10	**9**	**8**	**7**	**6**	**5**	**4**	**3**	**2**	**1**	

PIN DESIGNATIONS

CLK	=	Clock
GND	=	Ground
I	=	Input
I/O	=	Input/Output
N/C	=	No Connect
VCC	=	Supply Voltage
TDI	=	Test Data In
TCK	=	Test Clock
TMS	=	Test Mode Select
TDO	=	Test Data Out
$\overline{\text{TRST}}$	=	Test Reset
$\overline{\text{ENABLE}}$	=	Program

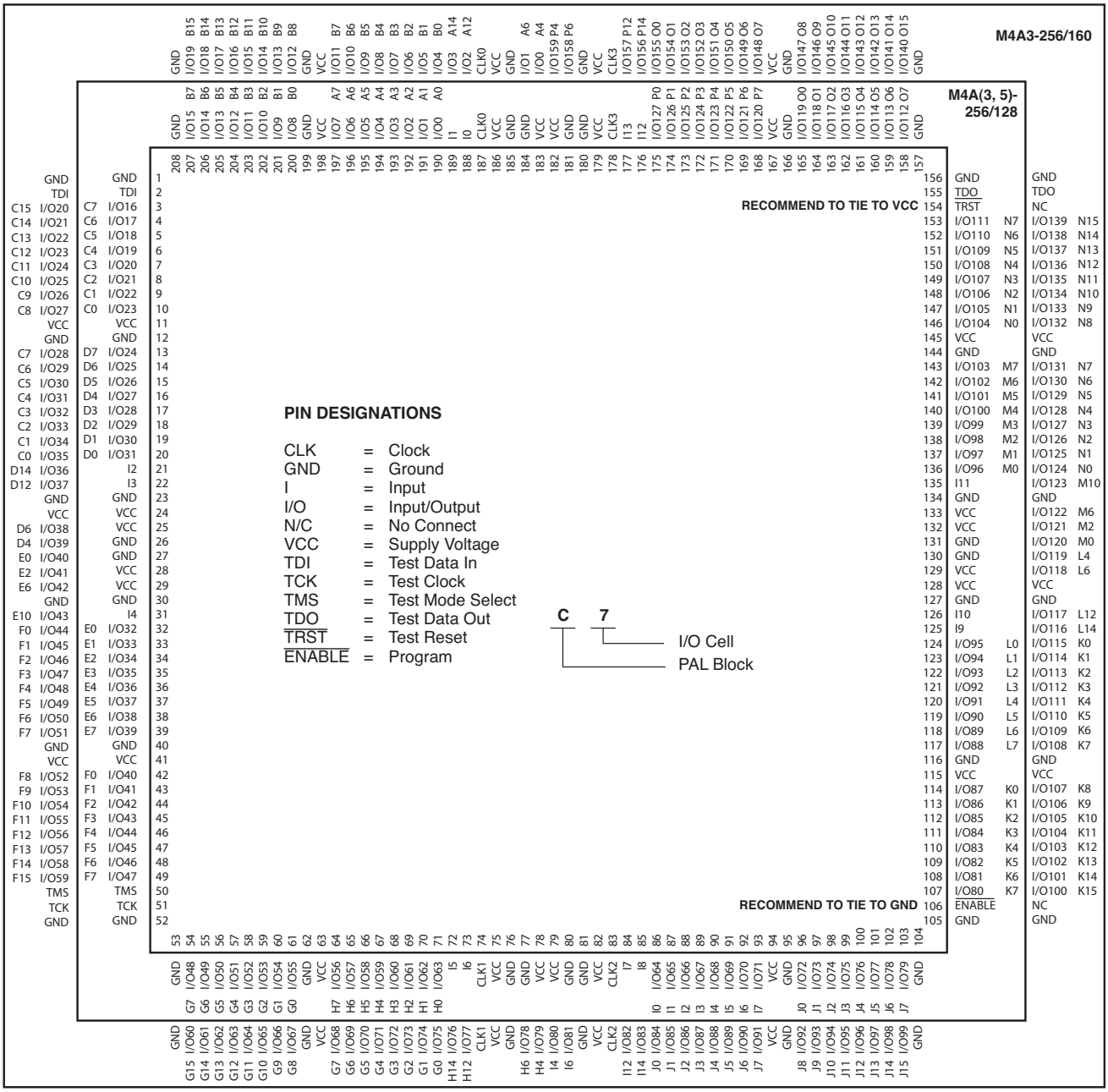


17466G-100cabga

208-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-256/128 AND M4A3-256/160)

Top View

208-Pin PQFP



17466G-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/128)

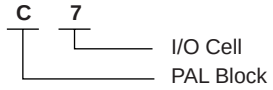
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	$\overline{\text{TRST}}$	I/O117 O5	I/O116 O4	I/O113 O1	I/O126 P6	I/O124 P4	I12	NC	NC	NC	CLK0	I/O1 A1	I/O5 A5	I/O7 A7	I/O10 B2	I/O12 B4	**A**
B	I/O110 N6	I/O111 N7	I/O118 O6	I/O115 O3	I/O127 P7	I/O125 P5	I/O120 P0	NC	NC	NC	I1	I/O2 A2	I/O8 B0	I/O11 B3	I/O13 B5	NC	**B**
C	I/O108 N4	I/O109 N5	NC	I/O119 O7	I/O114 O2	I/O122 P2	I/O123 P3	NC	NC	I0	I/O4 A4	I/O6 A6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	**C**
D	NC	I/O104 N0	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	**D**
E	I/O102 M6	NC	I/O107 N3	VCC	I/O105 N1	I/O106 N2	I13	CLK3	NC	NC	I/O0 A0	NC	GND	I/O20 C4	I/O19 C3	I/O31 D7	**E**
F	I/O98 M2	I/O103 M7	I/O101 M5	GND	I/O100 M4	I/O99 M3	I/O112 O0	I/O121 P1	NC	NC	I/O3 A3	I/O18 C2	VCC	I/O16 C0	I/O30 D6	I/O29 D5	**F**
G	NC	I/O96 M0	I11	VCC	NC	I/O97 M1	VCC	GND	GND	VCC	I/O17 C1	I/O28 D4	GND	I/O26 D2	I/O25 D1	I2	**G**
H	I/O88 L0	I10	I9	GND	I/O89 L1	I/O90 L2	GND	VCC	VCC	GND	I/O27 D3	I/O24 D0	VCC	NC	NC	NC	**H**
J	I/O91 L3	I/O92 L4	I/O93 L5	GND	I/O95 L7	I/O94 L6	GND	VCC	VCC	GND	I3	NC	GND	NC	NC	NC	**J**
K	NC	NC	NC	VCC	NC	NC	VCC	GND	GND	VCC	NC	NC	VCC	I4	NC	I/O32 E0	**K**
L	NC	NC	I/O80 K0	GND	I/O83 K3	NC	NC	NC	I/O59 H3	I/O61 H5	NC	NC	GND	I/O35 E3	I/O36 E4	I/O33 E1	**L**
M	I/O81 K1	I/O82 K2	I/O84 K4	GND	I/O67 I3	I/O65 I1	NC	NC	I/O58 H2	I/O48 G0	I/O51 G3	NC	VCC	I/O44 F4	I/O39 E7	I/O34 E2	**M**
N	I/O85 K5	I/O86 K6	$\overline{\text{ENABLE}}$	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O40 F0	I/O37 E5	**N**
P	I/O87 K7	I/O77 J5	I/O78 J6	I/O79 J7	I/O68 I4	I/O66 I2	NC	NC	NC	I6	I/O63 H7	I/O52 G4	I/O55 G7	TMS	I/O41 F1	I/O38 E6	**P**
R	I/O76 J4	I/O75 J3	I/O72 J0	I/O71 I7	I/O64 I0	I7	NC	NC	NC	I/O56 H0	I/O60 H4	I/O49 G1	I/O53 G5	I/O47 F7	I/O43 F3	I/O42 F2	**R**
T	I/O74 J2	I/O73 J1	I/O70 I6	I/O69 I5	I8	CLK2	NC	NC	CLK1	I5	I/O57 H1	I/O62 H6	I/O50 G2	I/O54 G6	I/O46 F6	I/O45 F5	**T**
	16	**15**	**14**	**13**	**12**	**11**	**10**	**9**	**8**	**7**	**6**	**5**	**4**	**3**	**2**	**1**	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
$\overline{\text{TDO}}$ = Test Data Out
$\overline{\text{TRST}}$ = Test Reset
$\overline{\text{ENABLE}}$ = Program



m4a3.256.128_256bga

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3- 256 / 128 -7 Y C

FAMILY TYPE

M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V_{CC})
M4A5- = ispMACH 4A Family Advanced Feature (5-V V_{CC})

MACROCELL DENSITY

32	= 32 Macrocells	192	= 192 Macrocells
64	= 64 Macrocells	256	= 256 Macrocells
96	= 96 Macrocells	384	= 384 Macrocells
128	= 128 Macrocells	512	= 512 Macrocells

I/Os

/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP
/48 = 48 I/Os in 100-pin TQFP
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA
/160 = 160 I/Os in 208-pin PQFP
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA
/256 = 256 I/Os in 388-ball fpBGA

*Package obsolete, contact factory.

SPEED

-5 = 5.0 ns t_{PD}
-55 = 5.5 ns t_{PD}
-6 = 6.0 ns t_{PD}
-65 = 6.5 ns t_{PD}
-7 = 7.5 ns t_{PD}
-10 = 10 ns t_{PD}
-12 = 12 ns t_{PD}
-14 = 14 ns t_{PD}

PACKAGE TYPE

SA = Ball Grid Array (BGA)
J = Plastic Leaded Chip Carrier (PLCC)
JN = Lead-free Plastic Leaded Chip Carrier (PLCC)
V = Thin Quad Flat Pack (TQFP)
VN = Lead-free Thin Quad Flat Pack (TQFP)
Y = Plastic Quad Flat Pack (PQFP)
YN = Lead-fee Plastic Quad Flat Pack (PQFP)
FA = Fine-pitch Ball Grid Array (fpBGA)
FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)
CA = Chip-array Ball Grid Array (caBGA)

OPERATING CONDITIONS

C = Commercial (0°C to +70°C)
I = Industrial (-40°C to +85°C)

48 = 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32

Conventional Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48
M4A3-64/32	-55, -7, -10	JC, VC, VC48
M4A3-64/64		VC
M4A3-96/48		VC
M4A3-128/64		YC, VC, CAC
M4A3-192/96	-6, -7, -10	VC, FAC
M4A3-256/128	-55, -65[1], -7, -10	YC, FAC, SAC
M4A3-256/160	-7, -10	YC
M4A3-256/192		FAC
M4A3-384/160	-65, -10, -12	YC
M4A3-384/192		SAC, FAC
M4A3-512/160	-7, -10, -12	YC
M4A3-512/192		FAC
M4A3-512/256		FAC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	JI, VI, VI48
M4A3-64/32		JI, VI, VI48
M4A3-64/64		VI
M4A3-96/48		VI
M4A3-128/64		YI, VI, CAI
M4A3-192/96		VI, FAI
M4A3-256/128		YI, FAI, SAI
M4A3-256/160	-10, -12	YI
M4A3-256/192		FAI
M4A3-384/160	-10, -12, -14	YI
M4A3-384/192		FAI
M4A3-512/160		YI
M4A3-512/192		FAI
M4A3-512/256		FAI

1. Use 5.5ns for new designs.

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32	-55, -7, -10	JC, VC, VC48
M4A5-96/48		VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JI, VI, VI48
M4A5-64/32	-7, -10, -12	JI, VI, VI48
M4A5-96/48		VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A3-64/64		VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160	-7, -10	YNC
M4A3-256/192		FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/32		VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96	-10, -12	VNI
M4A3-256/128		FANI, YNI
M4A3-256/160		YNI
M4A3-256/192	-10, -12, -14	FANI
M4A3-384/192		FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A5-96/48		VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-64/32		VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.